


Revision History

Revision	Date	Reason for redrawing	Page Update	Drawed	Checked	Approved
01A	2021.03.12	Preliminary	--	Tsunglin Yang		

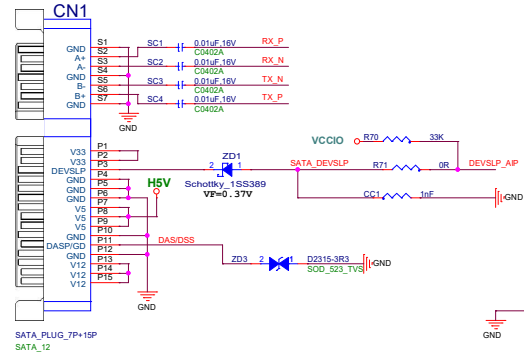
Model: SM2259XT-AB-G144\_2p5\_G152X4\_6L\_V01

Page1	Cover_Page
Page2	Controller_BGA144_2.5INCH
Page3	Power_Host_5V
Page4	NF_BGA152x4
Page5	Flash Mounting Guide

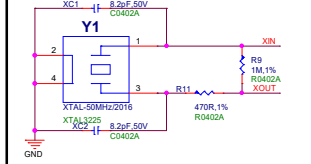
Silicon Motion, INC.

PageTitle		Cover Page	
DOC.Number		<Doc>	
Sch.FileName		SM2259XT2-F152x4 SHS DB V01A	
Date:		Thursday, July 01, 2021	
Sheet		1 of 5	
Rev		01A	

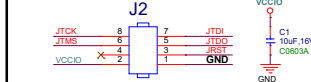
## SATA PLUG 7P+15P CONNECTOR



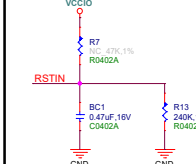
## Crystal



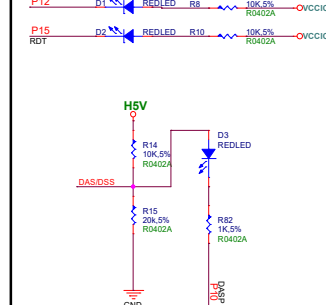
## JTAG Port



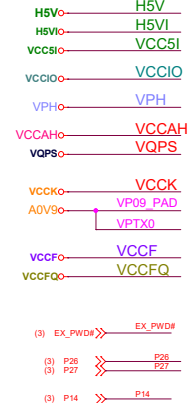
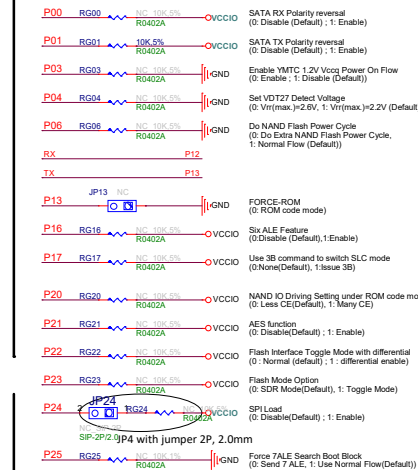
RESET



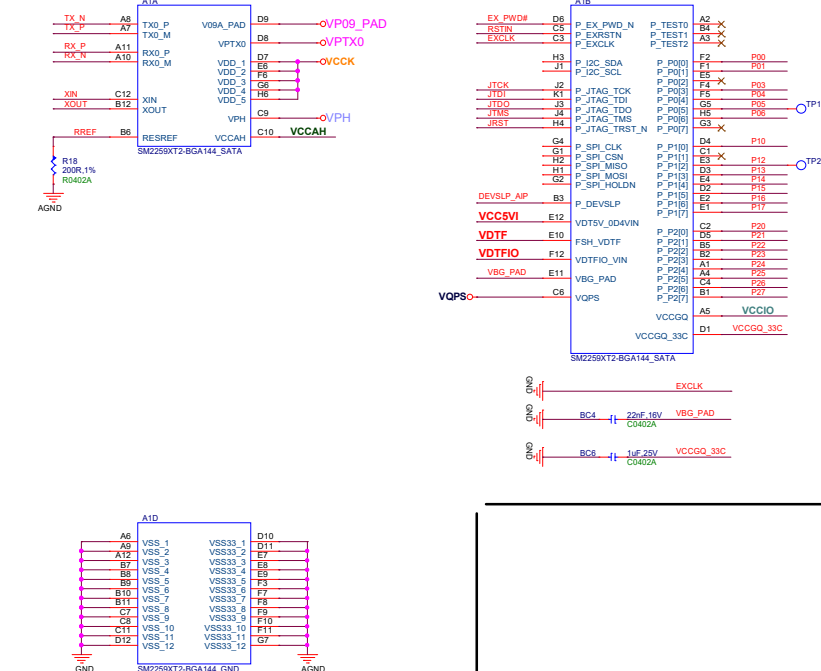
## LED function



### CPIO Definition



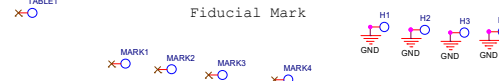
Controller  
SM2259XT-BGA144



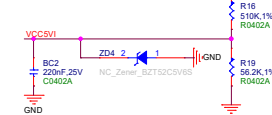
AIP



Fiducial Mark



## Voltage Detector



### Internal VDT for Flash Core Power

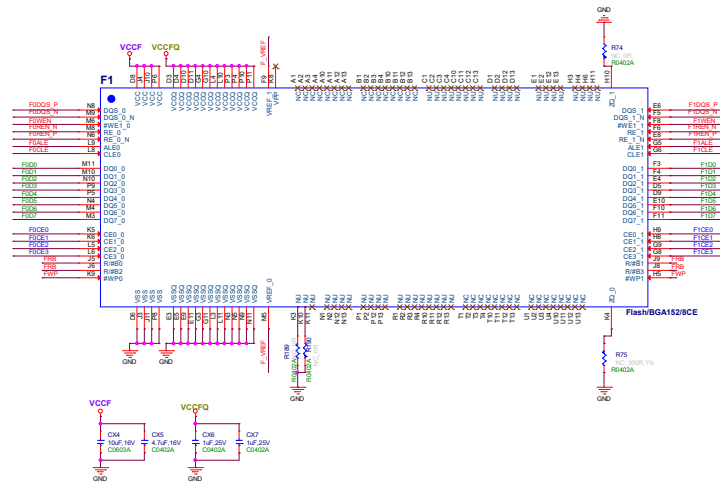


### Internal VDT for Flahs I/O

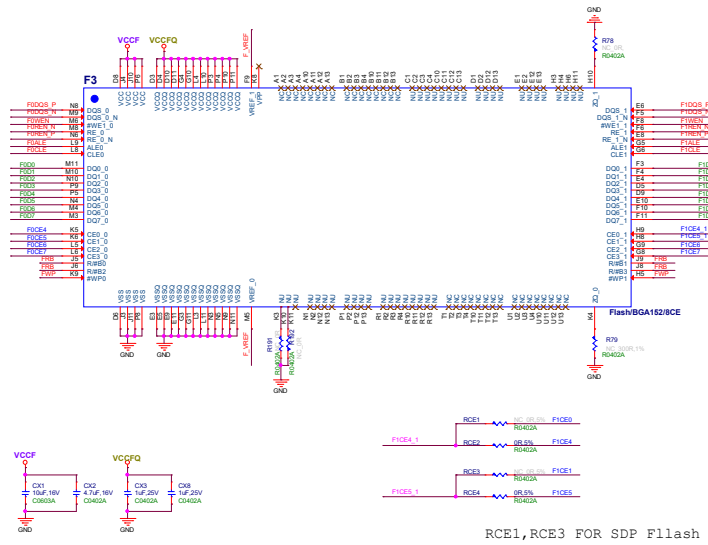




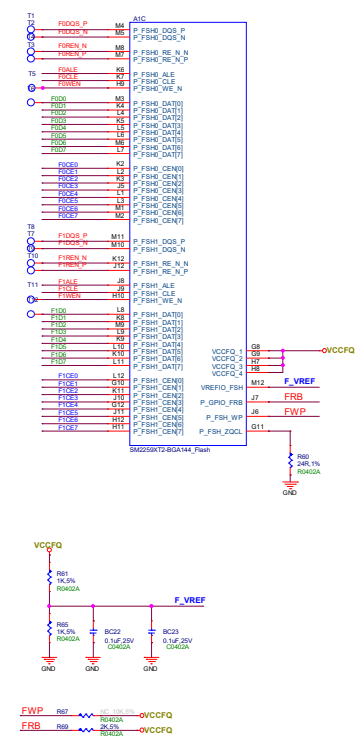
# Channel 0 & 1



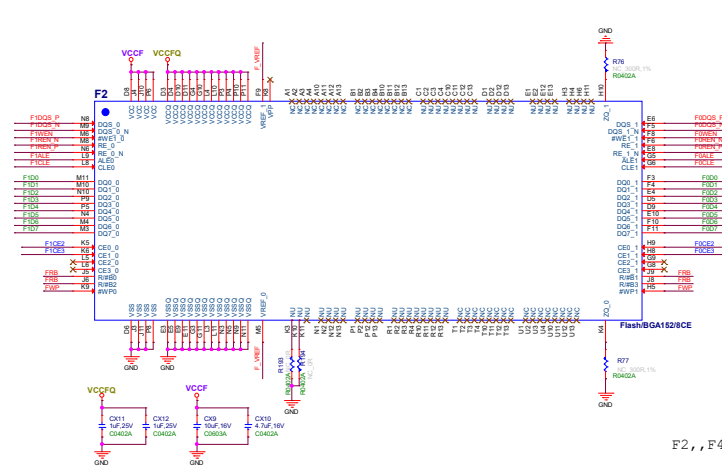
F1, F3 TOP Layer



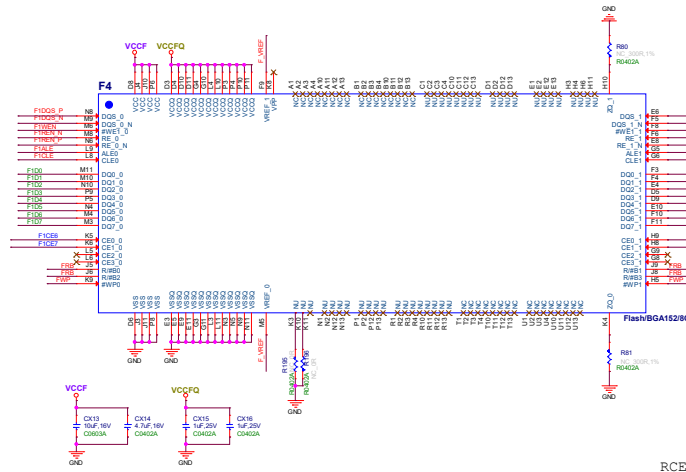
RCE1, RCE3 FOR SDP Flash



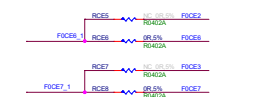
# Channel 0 & 1



F2, F4 BOTTOM Layer



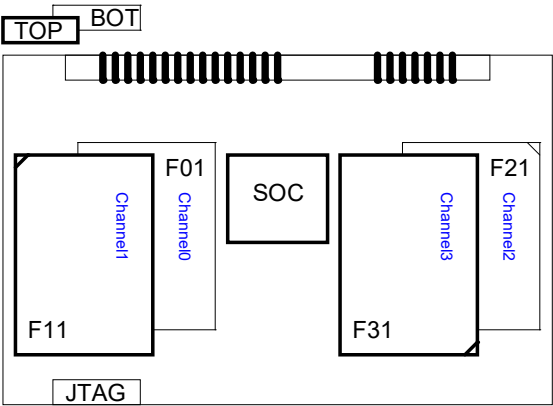
RCE5, RCE7 FOR SDP Flash



NAND FLASH Mounting Guide

Half-Slim BGA152X4 NAND Flash Mounting Guide													
NAND Flash Type	F1	F2	F3	F4	NF Config	RCE0	RCE1	RCE2	RCE3	RCE4	RCE5	RCE6	RCE7
Single CE Flash X1	○	×	×	×	1CH/1CE	➤	➤	➤	➤	➤	➤	➤	➤
Single CE Flash X2	○	○	×	×	2CH/1CE	○	➤	×	➤	➤	➤	➤	➤
Single CE Flash X4	○	○	○	○	2CH/2CE	○	➤	×	○	×	➤	○	➤
Dual CE Flash X1	○	×	×	×	2CH/1CE	➤	➤	➤	➤	➤	➤	➤	➤
Dual CE Flash X2	○	○	×	×	2CH/2CE	×	➤	○	➤	➤	➤	➤	➤
Dual CE Flash X4	○	○	○	○	2CH/4CE	×	➤	○	➤	×	➤	○	➤
1CH Dual CE X1	○	×	×	×	1CH/2CE	➤	➤	➤	➤	➤	➤	➤	➤
1CH Dual CE X2	○	○	×	×	2CH/2CE	○	○	×	×	➤	➤	➤	➤
1CH Dual CE X4	○	○	○	○	2CH/4CE	○	○	×	×	○	○	×	×
Quad CE Flash X1	○	×	×	×	2CH/2CE	➤	➤	➤	➤	➤	➤	➤	➤
Quad CE Flash X2	○	○	×	×	2CH/4CE	×	×	○	○	➤	➤	➤	➤
Quad CE Flash X4	○	○	○	○	2CH/8CE	×	×	○	○	×	×	○	○
Octo CE Flash X1	○	×	×	×	2CH/2CE	➤	➤	➤	➤	➤	➤	➤	➤
Octo CE Flash X2	○	×	×	×	2CH/4CE	➤	➤	➤	➤	➤	➤	➤	➤
						○	Install						
						×	Don't Use						
						➤	Don't Care						

TOP View For Flash PCB Placement



STACK UP

Layers Stack Up						P/N: 15080401-00							
類型 Type	結構 Construction	層別 Layer	假設的內層殘留率 (%) Assume Cu. Remain rate on inner layer(%)	材料型號 Material Type	ER (@2GHZ)	Thickness after laminate		Single Ended (50+/-5ohms)		Differential (100+/-10ohms)			Ref. Layer
						(mil)	(mm)	Line Width (mil)	Simulate (ohm)	Line Width (mil)	Spacing (mil)	Simulate (ohm)	
		Top Solder Mask		R500-MBLH(1)	3.8	1.00	0.025						
Metal		L1 - Signal		1/3OZ+PLATING		1.50	0.038	4.00	49.80	3.30	8.30	100.60	L2
Dielectric		Prepreg		1080	3.6	2.60	0.066						
Metal		L2 - GND	63.0%	0.5OZ		0.55	0.014						
Dielectric		Core		0.003"	4	3.00	0.076						
Metal		L3 - Signal	52.0%	0.5OZ		0.55	0.014	3.80	50.20				L2/L5
Dielectric		Prepreg		7628	4.2	7.84	0.199						
Metal		L4 - Signal	45.0%	0.5OZ		0.55	0.014	3.80	50.20	3.40	8.20	100.60	L2/L5
Dielectric		Core		0.003"	4	3.00	0.076						
Metal		L5 - VCC	61.0%	0.5OZ		0.55	0.014						
Dielectric		Prepreg		1080	3.6	2.60	0.066						
Metal	L6 - Signal			1/3OZ+PLATING		1.50	0.038	4.00	49.80	3.30	8.30	100.60	L5
		Bottom Solder Mask		R500-MBLH(1)	3.8	1.00	0.025						
Board thickness : 0.68+/-0.07mm						Total :	26.24	0.666					